

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

Microchannel Heat Pipe with Parallel Grooves for Recycling Coolant

the specification of which (check one)

☒ is attached hereto.

☐ was filed on

as Application Serial No.

and was amended on

(if applicable)

I hereby state that I have reviewed and understand the contents of the above identified specification, including the Claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, § 1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)

092104359

Taiwan, R.O.C.

2/27/03

Priority is Claimed:

☒ Yes

☐ No

(Number)

(Country)

(Day/Month/Year Filed)

☐ Yes

☐ No

(Number)

(Country)

(Day/Month/Year Filed)

☐ Yes

☐ No

(Number)

(Country)

(Day/Month/Year Filed)

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, § 1.56(a) which occurred between the filing date the prior application and the national or PCT international filing date of this application :

(Application Serial No.)

(Filing Date)

(Status)(patented, pending, abandoned)

(Application Serial No.)

(Filing Date)

(Status)(patented, pending, abandoned)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

POWER OF ATTORNEY: As a named inventor, I hereby appoint the following attorney(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith. (list name & registration no.)

**Hung-Chang LIN, U.S. Patent Agent (Registration No. 28,789)**

Send Correspondence to :

**H.C. LIN**

**8 Schindler Court, Silver Spring, Maryland 20903.**

Direct Telephone Calls to : (name & telephone number)

**H.C. LIN, (301)434-3571**

Full name of sole or first inventor

**Shwin-Chung, WONG**

Inventor's signature

**Date: January 15, 2004**

Residence

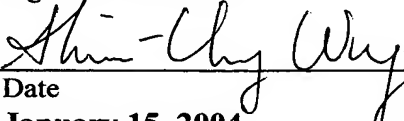
**4F., No.11, Alley 52, Chincheng 1st Road, Hsinchu 30056, Taiwan**

Citizenship

**the Republic of China.**

Post Office Address

**4F., No.11, Alley 52, Chincheng 1st Road, Hsinchu 30056, Taiwan**

<b>VERIFIED STATEMENT CLAIMING SMALL ENTITY STATUS (37 CFR 1.9(f) &amp; 1.27(b))—INDEPENDENT INVENTOR</b>		Docket Number. <b>Wong 9301</b>
Applicant or Patentee:	<b>Shwin-Chung, WONG</b>	
Serial or Patent No.:		
Filed or Issued:		
Title:	<b>Microchannel Heat Pipe with Parallel Grooves for Recycling Coolant</b>	
<p>As a below named inventor, I hereby declare that I qualify as an independent inventor as defined in 37 CFR 1.9(c) for purposes of paying reduced fees to the Patent and Trademark Office described in:</p> <p><input checked="" type="checkbox"/> the specification filed herewith with title as listed above.</p> <p><input type="checkbox"/> the application identified above.</p> <p><input type="checkbox"/> the patent identified above.</p> <p>I have not assigned, granted, conveyed or licensed and am under no obligation under contract or law to assign, grant, convey or license, any rights in the invention to any person who would not qualify as an independent inventor under 37 CFR 1.9(C) if that person had made the invention, or to any concern which would not qualify as a small business concern under 37 CFR 1.9(d) or a nonprofit organization under 37 CFR 1.9(e).</p> <p>Each person, concern or organization to which I have assigned, granted, Conveyed, or licensed or am under an obligation under contract or law to assign, grant, convey, or license any rights in the invention is listed below:</p> <p><input checked="" type="checkbox"/> No such person, concern, or organization exists.</p> <p><input type="checkbox"/> Each such person, concern or organization is listed below.</p> <p>Separate verified statements are required from each named person, concern or organization having rights to the invention averring to their status as small entities. (37 CFR 1.27)</p> <p>I acknowledge the duty to file, in this application or patent, notification of any change in status resulting in loss of entitlement to small entity status prior to paying, or at the time of paying, the earliest of the issue fee or any maintenance fee due after the date on which status as a small entity is no longer appropriate. (37 CFR 1.28(b))</p> <p>I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like to made are punishable by fine or imprisonment, or both, under section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application, any patent issuing thereon, or any patent to which this verified statement is directed.</p>		
NAME OF INVENTOR	NAME OF INVENTOR	NAME OF INVENTOR
<b>Shwin-Chung, WONG</b>		
Signature of inventor	Signature of inventor	Signature of inventor
		
Date	Date	Date
<b>January 15, 2004</b>		